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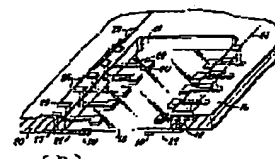
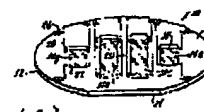
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(54) MULTIPORT THIN FILM PROBE FOR TESTING WAFER ENTIRELY

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a probe for testing multiple integrated circuit chips simultaneously.

SOLUTION: The multi port thin film probe comprises a rigid substrate 12 provided with a plurality of elongated ports 14a, c, e, g having width not larger than 1.5 times of the lateral dimension of a chip, a flexible transparent thin film 18 extending across the elongated ports, a plurality of conductive traces 22 formed on the thin film 18, and contact pads 30 formed on selected traces and arranged in the elongated port of the thin film.



## LEGAL STATUS

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